

What Is Claimed Is:

1. A method for forming a laminated structure by connecting a first substrate to a second substrate with a plurality of particles and an intermediate, the first substrate having a first conjunction portion and a second conjunction portion and the second substrate having a third conjunction portion and a fourth conjunction portion, comprising the steps of:

applying the particles on the third conjunction portion and the fourth conjunction portion;

applying the intermediate between the first substrate and the second substrate;

bringing the first substrate and the second substrate close to each other to clamp the intermediate between; and

contacting the particles located on the third conjunction portion and the fourth conjunction portion on the first conjunction portion and the second conjunction portion.

2. The method for forming a laminated structure as claimed in Claim 1, wherein the third conjunction and the fourth conjunction are two bumps protruded from the second substrate.

3. The method for forming a laminated structure as claimed in Claim 1, wherein the third conjunction portion and the fourth conjunction portion are provided with the first hardness, and the particles are provided with a second hardness greater than the first hardness.

4. The method for forming a laminated structure as claimed in Claim 1, wherein the particles are partially made of conductive material.

5. The method for forming a laminated structure as claimed in Claim 1, wherein the particles are made of

nickel and the first conjunction portion are made of gold.

6. The method for forming a laminated structure as claimed in Claim 1, wherein the intermediate is made of rubber.